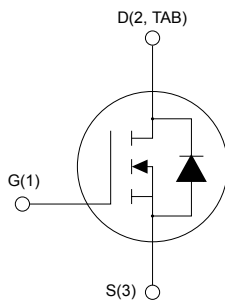
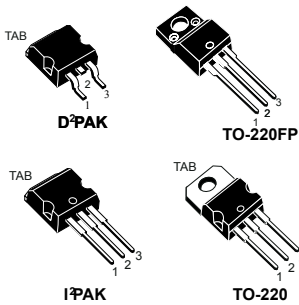




STB21N65M5, STF21N65M5 STI21N65M5, STP21N65M5

Datasheet

N-channel 650 V, 150 mΩ typ., 17 A MDmesh M5 Power MOSFETs in a D²PAK, TO-220FP, I²PAK and TO-220 packages



AM01475v1_noZen



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STB21N65M5	650 V	179 mΩ	17 A
STF21N65M5			
STI21N65M5			
STP21N65M5			

- Higher V_{DSS} rating
- Higher dv/dt capability
- Excellent switching performance
- Extremely low R_{DS(on)}
- 100% avalanche tested

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs based on the MDmesh M5 innovative vertical process technology combined with the well-known PowerMESH horizontal layout. The resulting products offer extremely low on-resistance, making them particularly suitable for applications requiring high power and superior efficiency.

Product status links

[STB21N65M5](#)

[STF21N65M5](#)

[STI21N65M5](#)

[STP21N65M5](#)

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		D ² PAK I ² PAK TO-220	TO-220FP	
V _{GS}	Gate-source voltage	±25		V
I _D	Drain current (continuous) at T _C = 25 °C	17		A
I _D	Drain current (continuous) at T _C = 100 °C	10.7		A
I _{DM} ⁽¹⁾	Drain current (pulsed)	68		A
P _{TOT}	Total power dissipation at T _C = 25 °C	125	30	W
dv/dt ⁽²⁾	Peak diode recovery voltage slope	15		V/ns
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T _C = 25 °C)	-	2.5	kV
T _{stg}	Storage temperature range	-55 to 150		°C
T _J	Operating junction temperature range	150		°C

1. Pulse width limited by safe operating area.
2. I_{SD} ≤ 17 A, di/dt ≤ 400 A/μs; V_{DS (peak)} < V_{(BR)DSS}, V_{DD} = 400 V.

Table 2. Thermal data

Symbol	Parameter	Value			Unit
		D ² PAK	I ² PAK TO-220	TO-220FP	
R _{thJC}	Thermal resistance, junction-to-case	1		4.17	°C/W
R _{thJA}	Thermal resistance, junction-to-ambient	30 ⁽¹⁾	62.5		°C/W

1. When mounted on a standard 1 inch² area of FR-4 PCB with 2-oz copper.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T _J max.)	5	A
E _{AS}	Single pulse avalanche energy (starting T _J = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	400	mJ

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified.

Table 4. On/off states

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	650	-	-	V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 650\text{ V}$	-	-	1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 650\text{ V}$, $T_C = 125\text{ °C}^{(1)}$	-	-	100	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 25\text{ V}$	-	-	100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 8.5\text{ A}$	-	150	179	m Ω

1. Specified by design, not tested in production.

Table 5. Dynamic

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	1950	-	μF
C_{oss}	Output capacitance		-	46	-	
C_{rss}	Reverse transfer capacitance		-	3	-	
$C_{o(tr)}^{(1)}$	Equivalent output capacitance time related	$V_{DS} = 0\text{ to }520\text{ V}$, $V_{GS} = 0\text{ V}$	-	133	-	μF
$C_{o(er)}^{(2)}$	Equivalent output capacitance energy related		-	44	-	μF
R_g	Gate input resistance	$f = 1\text{ MHz}$ open drain	-	2.5	-	Ω
Q_g	Total gate charge	$V_{DD} = 520\text{ V}$, $I_D = 8.5\text{ A}$,	-	50	-	nC
Q_{gs}	Gate-source charge	$V_{GS} = 0\text{ to }10\text{ V}$	-	13	-	
Q_{gd}	Gate-drain charge	(see the Figure 17. Test circuit for gate charge behavior)	-	23	-	

1. $C_{o(tr)}$ is an equivalent capacitance that provides the same charging time as C_{oss} while V_{DS} is rising from 0 V to the stated value.

2. $C_{o(er)}$ is an equivalent capacitance that provides the same stored energy as C_{oss} while V_{DS} is rising from 0 V to the stated value.

Table 6. Switching times

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off delay time	$V_{DD} = 400\text{ V}$, $I_D = 11\text{ A}$,	-	37	-	ns
$t_{r(v)}$	Voltage rise time	$R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$	-	10	-	
$t_{c(off)}$	Crossing time off	(see the Figure 18. Test circuit for inductive load switching and diode recovery times and Figure 21. Switching time waveform)	-	24	-	
$t_{f(i)}$	Current fall time		-	12	-	

Table 7. Source-drain diode

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-	-	17	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-	-	68	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 17\text{ A}$, $V_{GS} = 0\text{ V}$	-	-	1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 17\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$	-	294	-	ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 100\text{ V}$ (see the Figure 18. Test circuit for inductive load switching and diode recovery times)	-	4	-	μC
I_{RRM}	Reverse recovery current		-	28	-	A
t_{rr}	Reverse recovery time	$I_{SD} = 17\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$	-	340	-	ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 100\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see the Figure 18. Test circuit for inductive load switching and diode recovery times)	-	5	-	μC
I_{RRM}	Reverse recovery current		-	29	-	A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

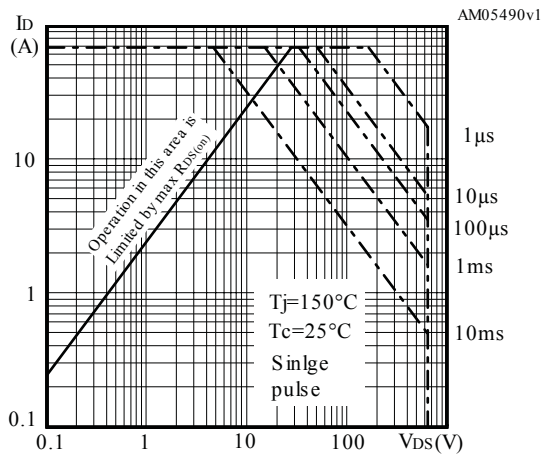
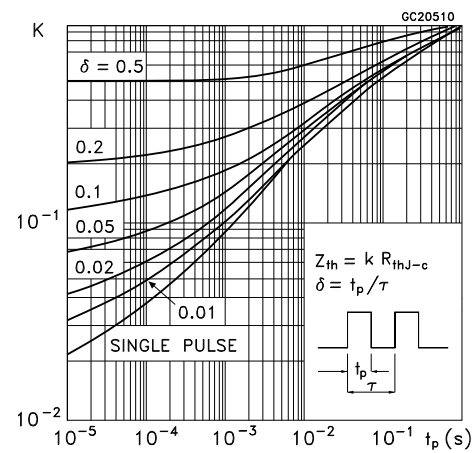
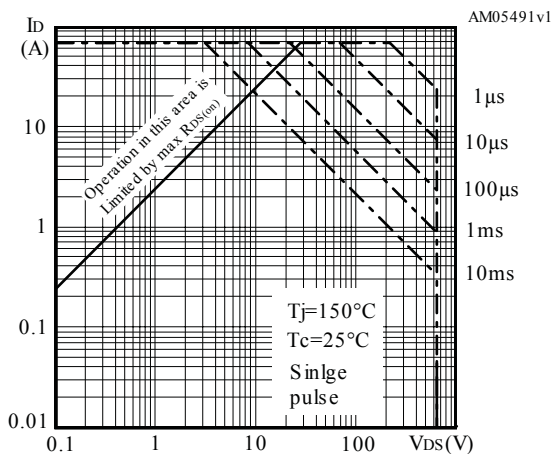
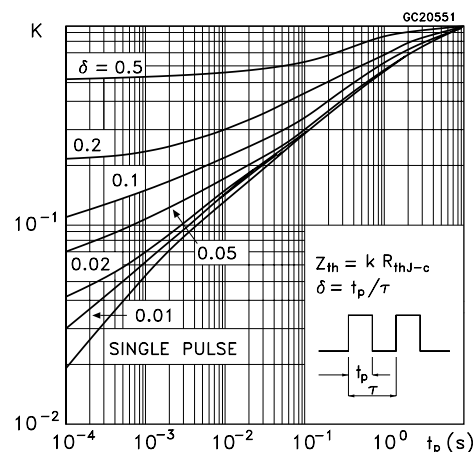
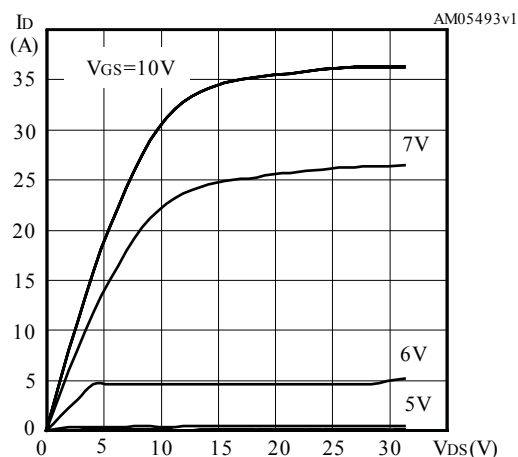
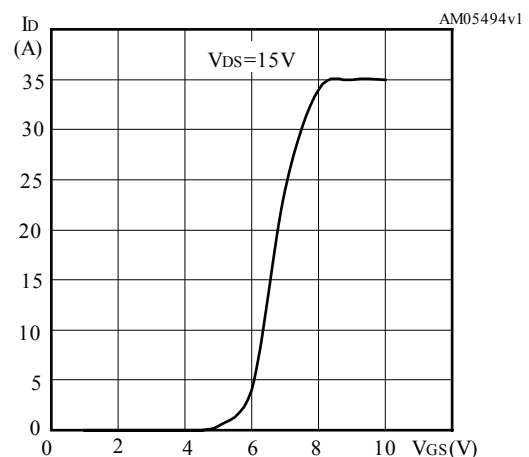
2.1 Electrical characteristics (curves)
Figure 1. Safe operating area for D²PAK, I²PAK and TO-220

Figure 2. Normalized transient thermal impedance for D²PAK, I²PAK and TO-220

Figure 3. Safe operating area for TO-220FP

Figure 4. Normalized transient thermal impedance for TO-220FP

Figure 5. Output characteristics

Figure 6. Transfer characteristics


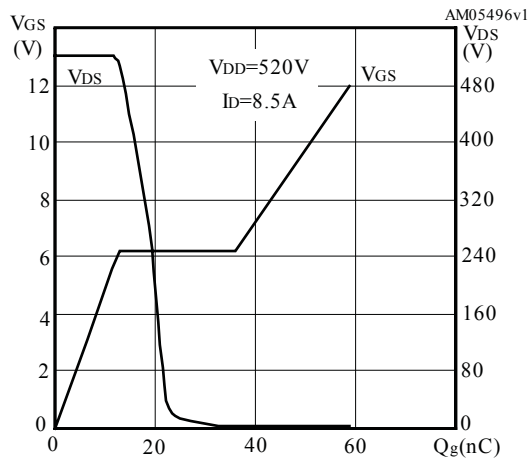
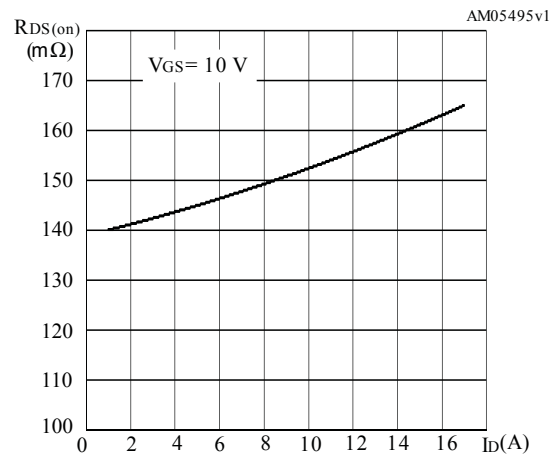
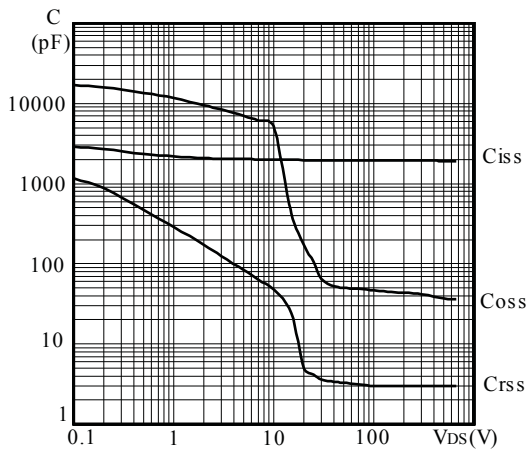
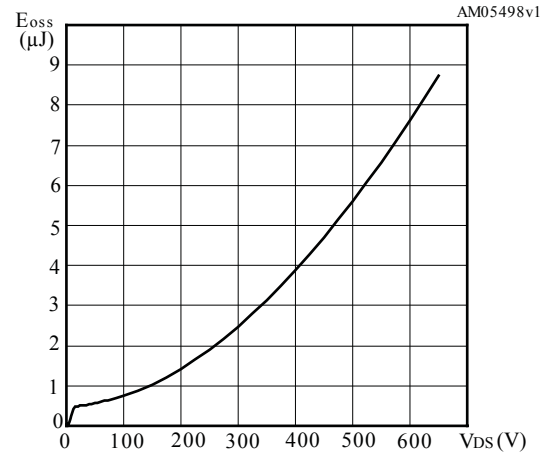
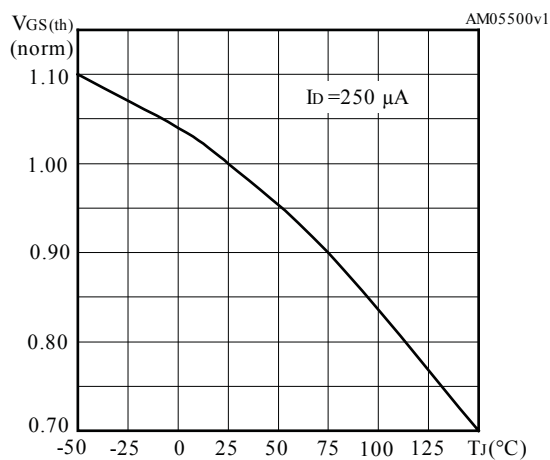
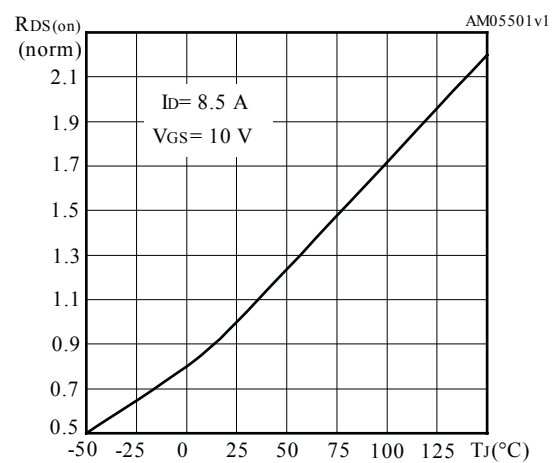
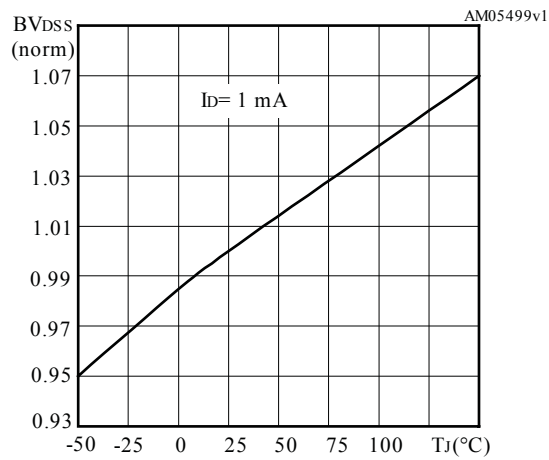
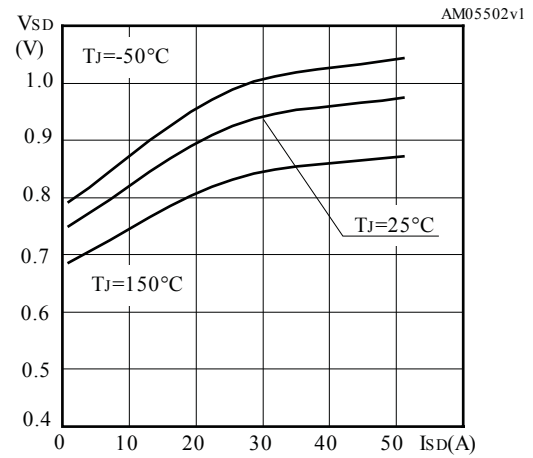
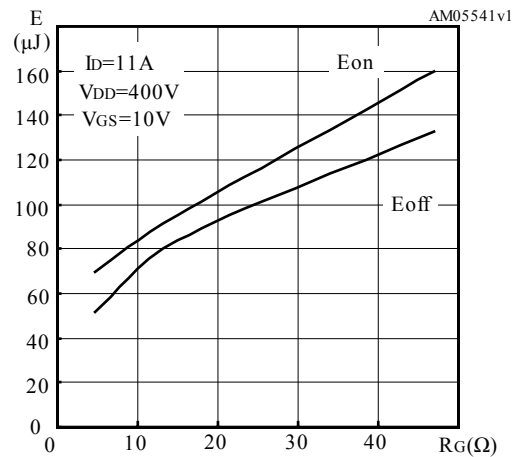
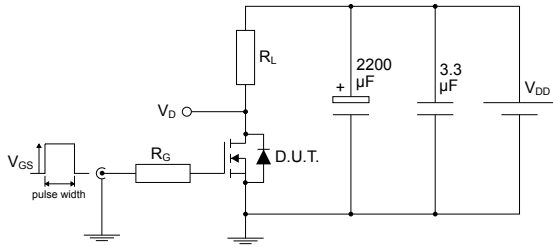
Figure 7. Gate charge vs gate-source voltage

Figure 8. Static drain-source on-resistance

Figure 9. Capacitance variations

Figure 10. Output capacitance stored energy

Figure 11. Normalized gate threshold voltage vs temperature

Figure 12. Normalized on-resistance vs temperature


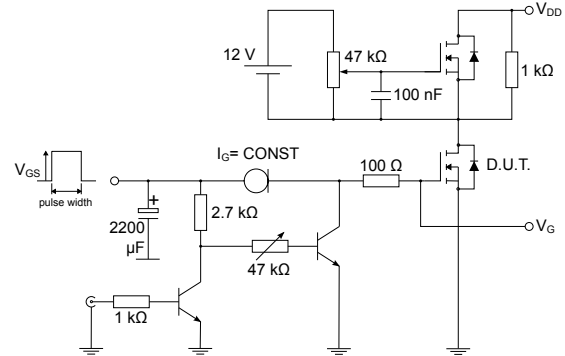
Figure 13. Normalized $V_{(BR)DSS}$ vs temperature

Figure 14. Drain-source diode forward characteristics

Figure 15. Switching energy vs gate resistance


Note: E_{on} including reverse recovery of a SiC diode.

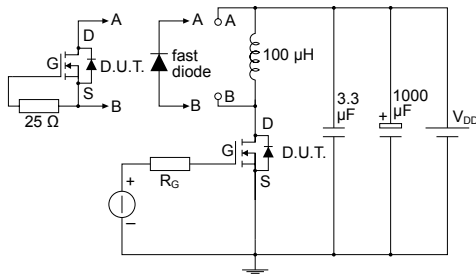
3 Test circuits

Figure 16. Test circuit for resistive load switching times


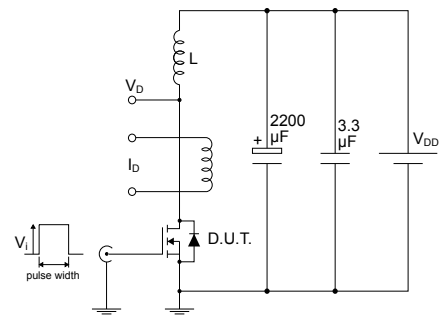
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Figure 17. Test circuit for gate charge behavior


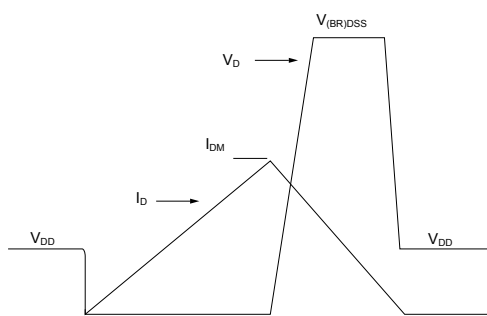
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Figure 18. Test circuit for inductive load switching and diode recovery times


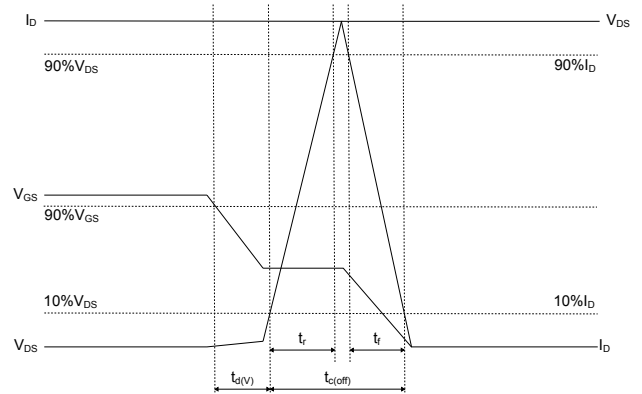
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Figure 19. Unclamped inductive load test circuit


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Figure 20. Unclamped inductive waveform


AM01472v1

Figure 21. Switching time waveform


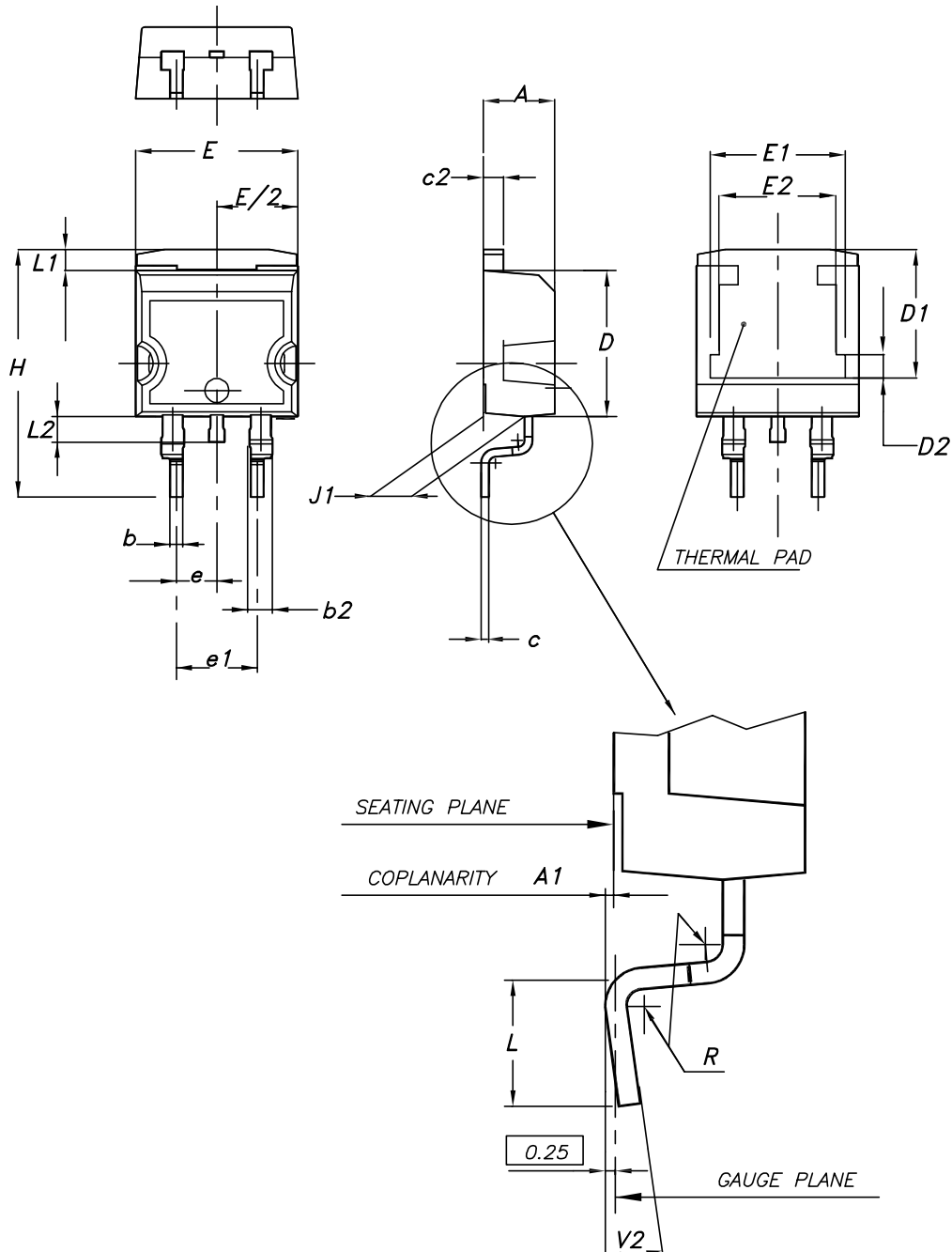
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4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A package information

Figure 22. D²PAK (TO-263) type A package outline



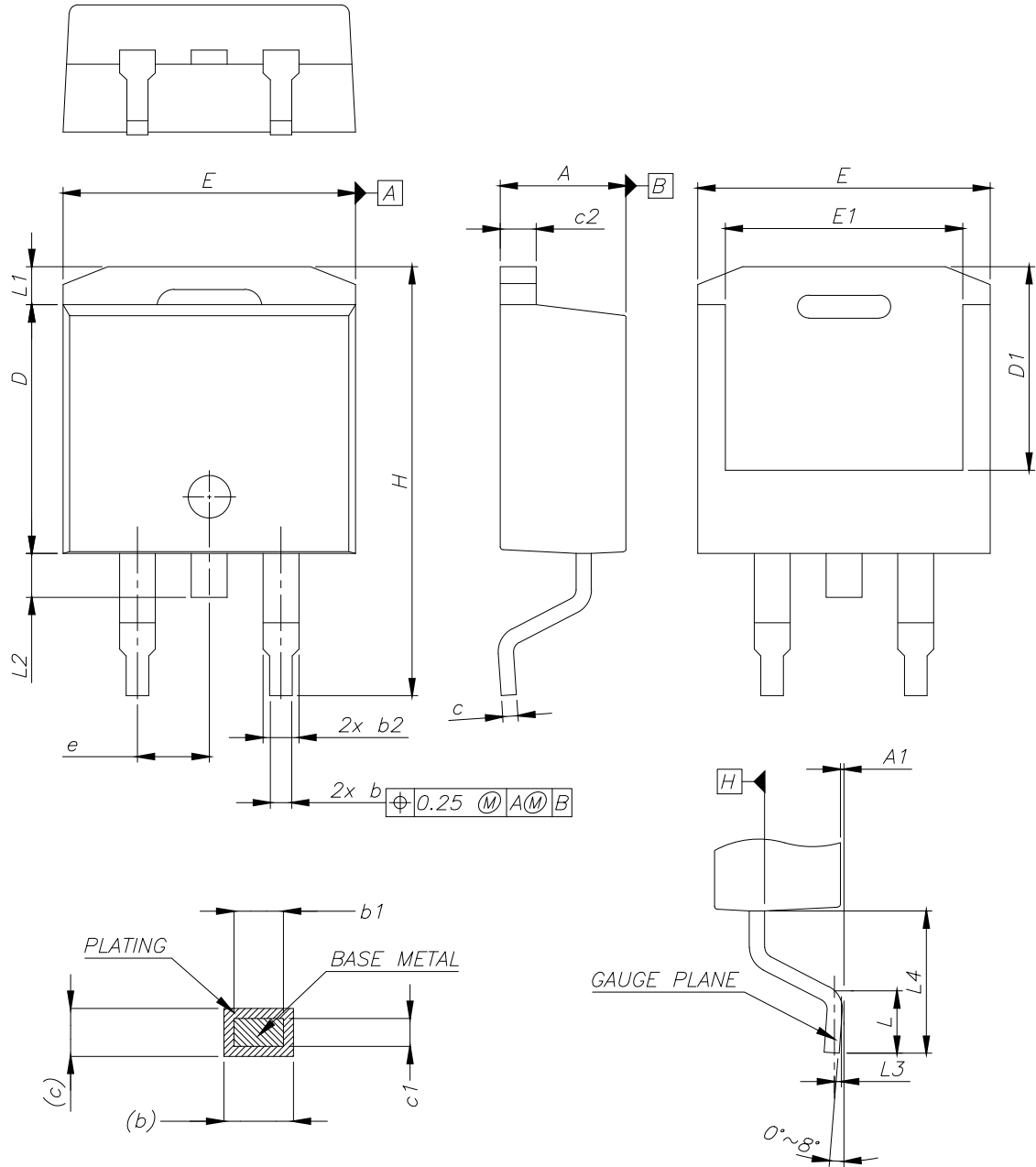
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Table 8. D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.30	8.50	8.70
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

4.2 D²PAK (TO-263) type B package information

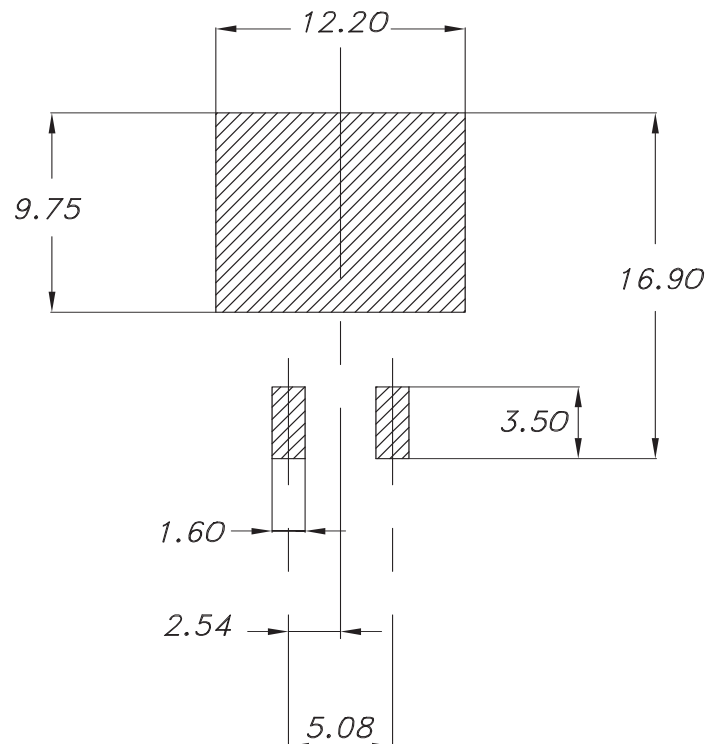
Figure 23. D²PAK (TO-263) type B package outline



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Table 9. D²PAK (TO-263) type B mechanical data

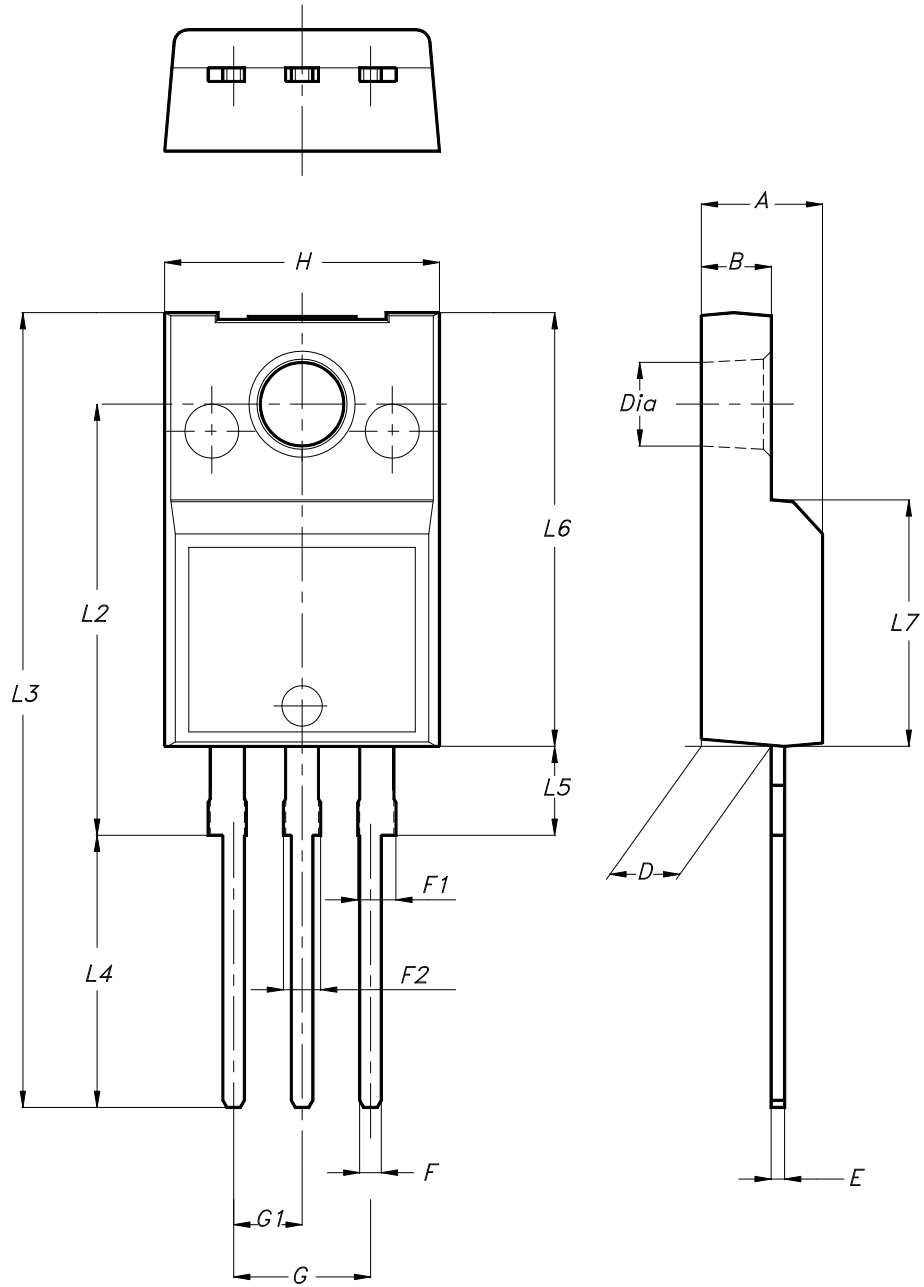
Dim.	mm		
	Min.	Typ.	Max.
A	4.36		4.56
A1	0.00		0.25
b	0.70		0.90
b1	0.51		0.89
b2	1.17		1.37
c	0.38		0.694
c1	0.38		0.534
c2	1.19		1.34
D	8.60		9.00
D1	6.90		7.50
E	10.15		10.55
E1	8.10		8.70
e	2.54 BSC		
H	15.00		15.60
L	1.90		2.50
L1			1.65
L2			1.78
L3		0.25	
L4	4.78		5.28

Figure 24. D²PAK (TO-263) recommended footprint (dimensions are in mm)


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4.3 TO-220FP type B package information

Figure 25. TO-220FP type B package outline



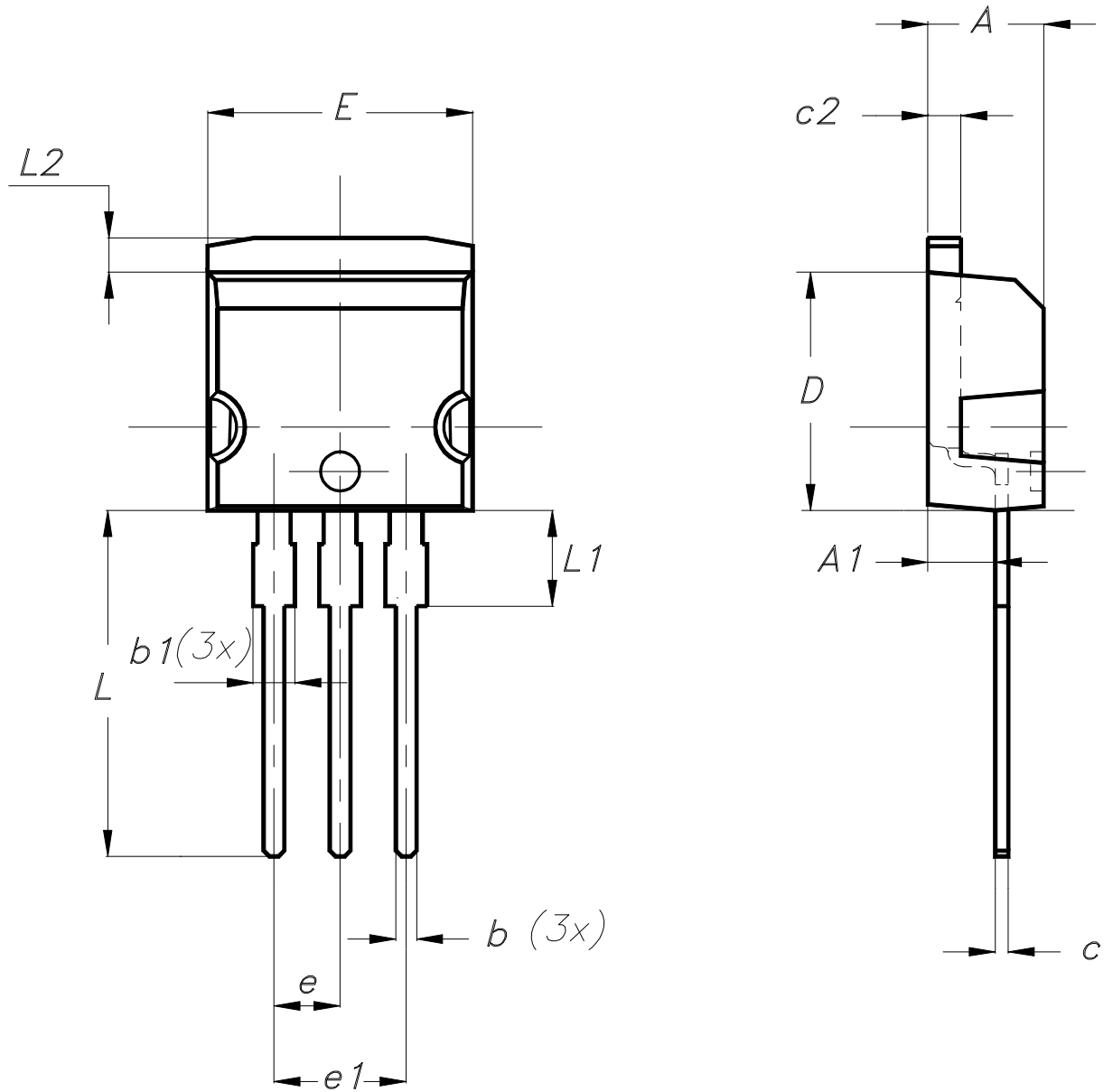
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Table 10. TO-220FP type B package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.4 I²PAK package information

Figure 26. I²PAK package outline



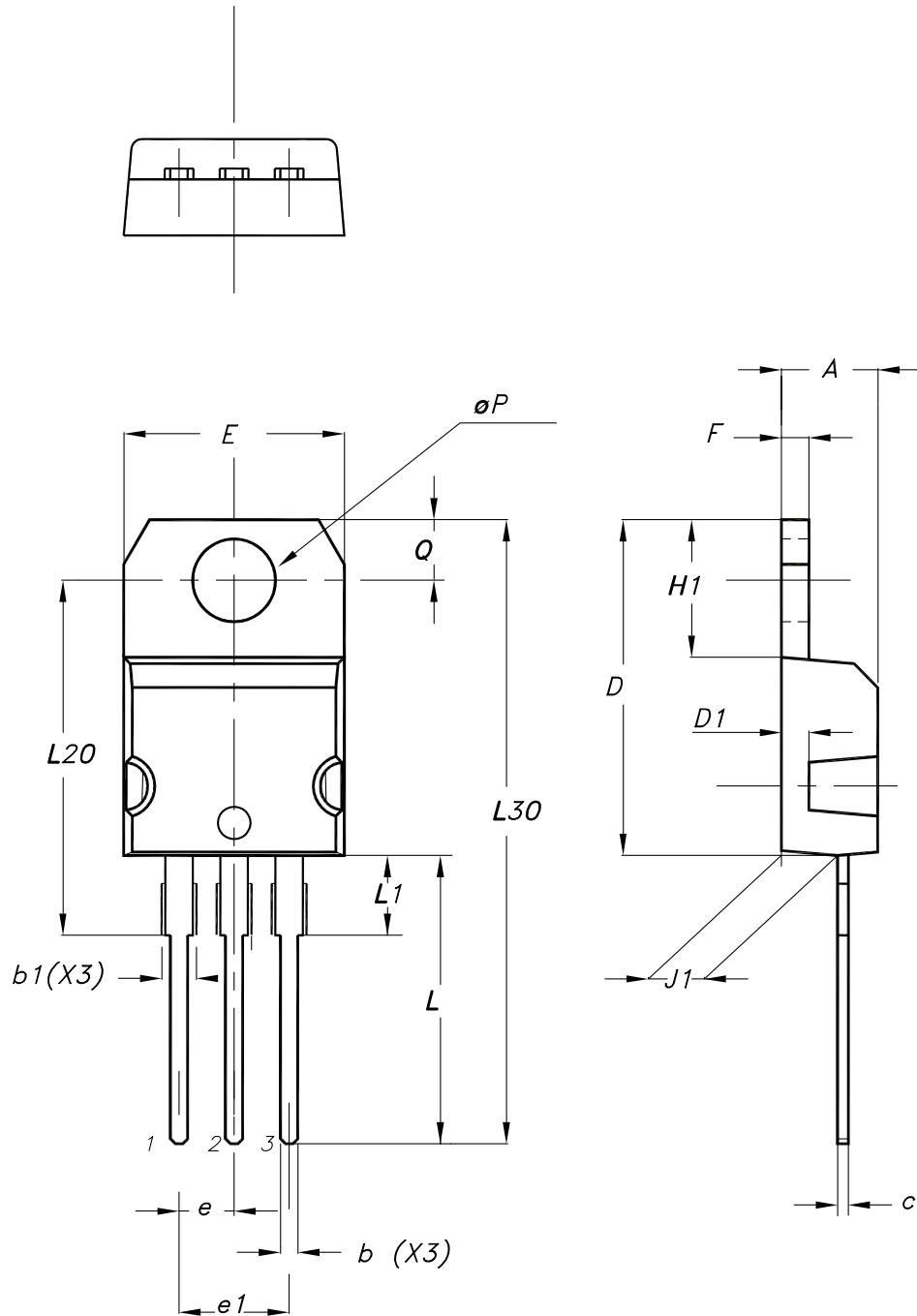
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Table 11. I²PAK package mechanical data

Dim.	mm	
	Min.	Max.
A	4.40	4.60
A1	2.40	2.72
b	0.61	0.88
b1	1.14	1.70
c	0.49	0.70
c2	1.23	1.32
D	8.95	9.35
e	2.40	2.70
e1	4.95	5.15
E	10.00	10.40
L	13.00	14.00
L1	3.50	3.93
L2	1.27	1.40

4.5 TO-220 type A package information

Figure 27. TO-220 type A package outline



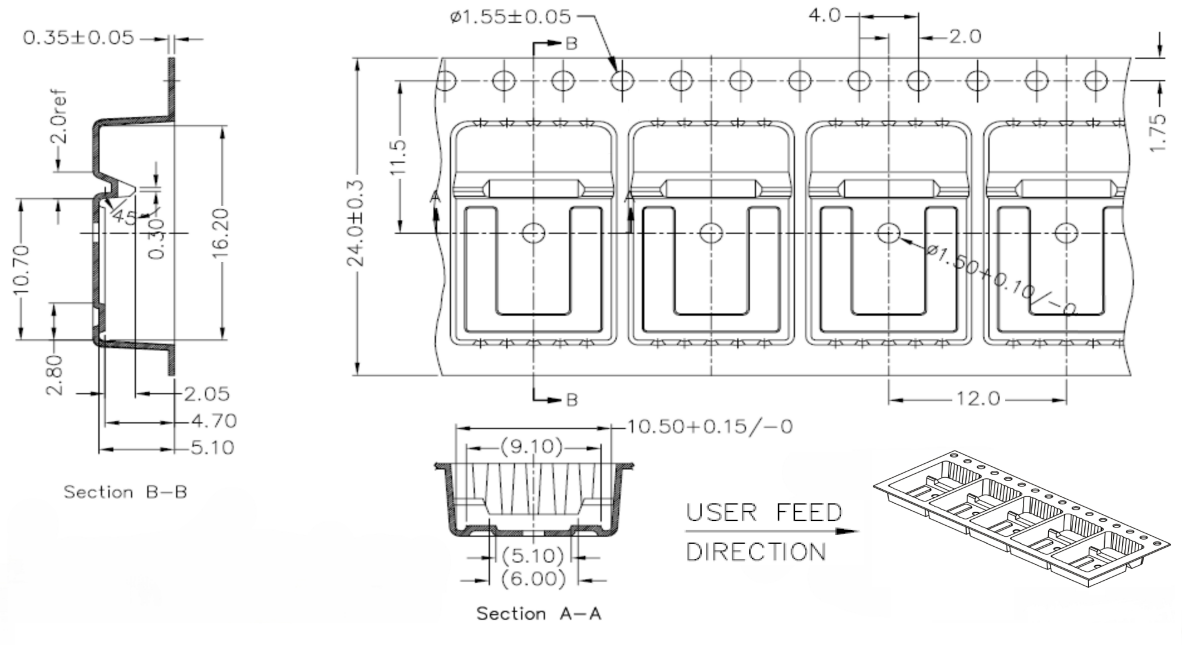
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Table 12. TO-220 type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

4.6 D²PAK packing information

Figure 28. D²PAK tape drawing (dimensions are in mm)



DM01095771_2



5 Ordering information

Table 13. Order codes

Order codes	Marking	Package	Packing
STB21N65M5	21N65M5	D ² PAK	Tape and reel
STF21N65M5		TO-220FP	Tube
STI21N65M5		I ² PAK	
STP21N65M5		TO-220	

Revision history

Table 14. Document revision history

Date	Revision	Changes
24-Feb-2009	1	First release.
27-Feb-2009	2	Corrected package information on first page.
11-Nov-2009	3	Document status promoted from preliminary data to datasheet.
11-May-2011	4	RDS(on) values have been updated (see <i>Table 4: On /off states</i> and <i>Figure 11: Static drain-source on resistance</i>).
01-Aug-2025	5	Removed order code STW21N65M5. Updated Section 4: Package information . Minor text changes.



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4.2	D ² PAK (TO-263) type B package information	11
4.3	TO-220FP type B package information	13
4.4	I ² PAK package information	15
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